

Notice of References Cited	Application/Control No. 10/728,068	Applicant(s)/Patent Under Reexamination STEINMANN ET AL.	
	Examiner Nghia M. Doan	Art Unit 2825	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

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	V	Richard et al., Thermal Properties of Very Fast Transistors, August, 1970, IEEE Transactions on Electron Devices, Vol. 17, No. 8, Pages 586-594
	W	Chung et al., Junction-to-Top and Junction-to-Board Thermal Resistance- Measurement for 119 BGA Packages, May, 1999, Fifteenth IEEE SEMI-THERM Symposium, Page 142-150
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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